## AITSUBISHI MATERIALS

Copper & Copper Alloy Business

#### **Products Information**

#### Features

- Low insertion/removal force of connectors, dynamic friction coefficient is up to around 30% lower than conventional reflow Sn plating (Conventional plating)
- Large amounts of Tin (Sn) are left between Cu-Sn intermetallic compound (IMC), achieving excellent electrical connection reliability
- Available for various copper and copper alloys, such as Cu-Mg-based copper alloy, MSP series

#### >Application examples

□ Small terminals for automotive multipole connectors

#### Dynamic friction coefficient



### 🙏 MITSUBISHI MATERIALS

URL:http://www.mitsubishi-copper.com/en/ Date: 15/12/2021

# **PIC Plating**

Reflow Sn plating for low insertion / removal force

#### Structure of plating

- Cu-Sn IMC is precisely controlled to form columnar grains exposed homogeneously to the surface
- □ Large amounts of Sn are left between Cu-Sn IMC grains





The white parts are Cu-Sn IMC

#### Surface images of plating

#### Heat resistance



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